

Features

- Ultra low capacitance: 0.4pF(IO to GND)
- Ultra low leakage: nA level
- Low operating voltage: 3.3V
- Low clamping voltage
- Protects one power line and four data lines
- Flow-through package
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
Air discharge: $\pm 25\text{kV}$
Contact discharge: $\pm 20\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 4A (8/20 μs)
- RoHS Compliant
- Rclamp3304P pin to pin fully compatible

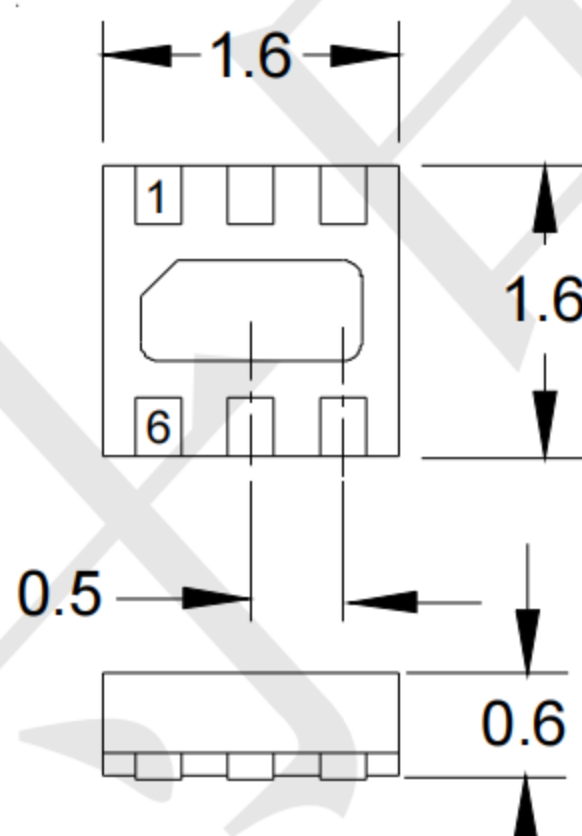
Mechanical Characteristics

- Package: DFN1616-6
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Shipping Qty :3000pcs/7Inch Tape & Reel

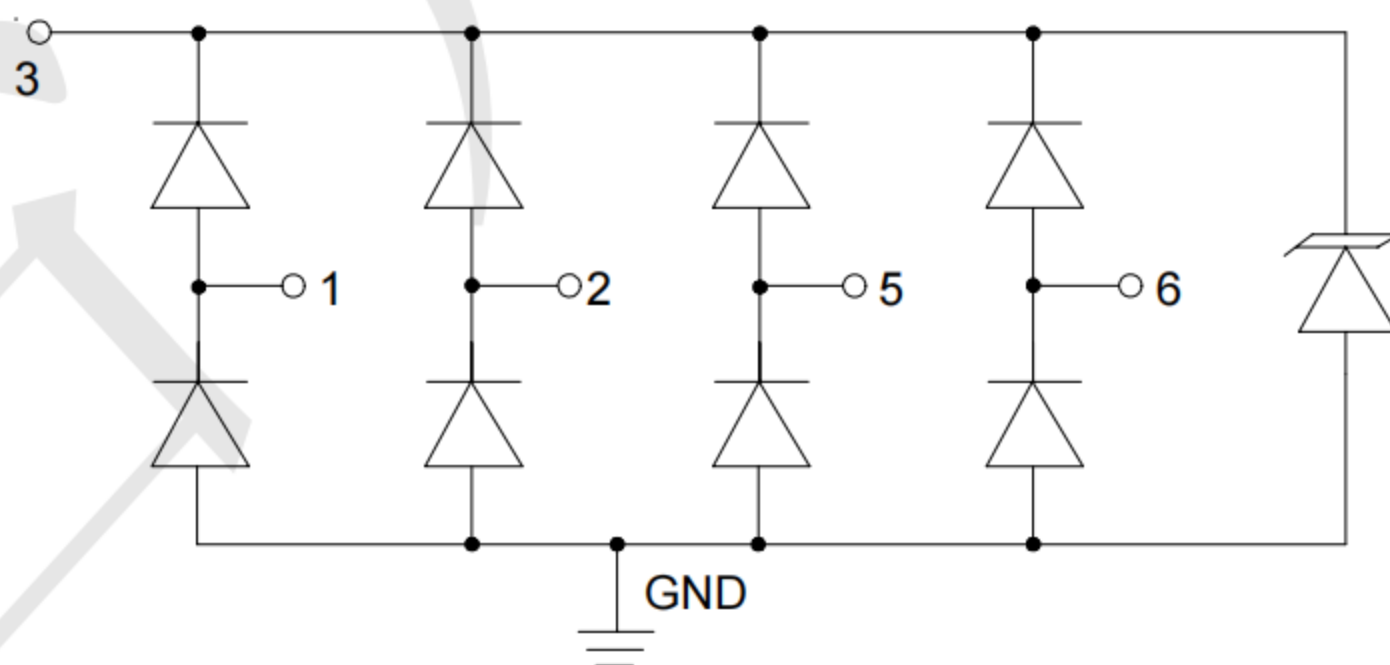
Applications

- Multi Media Card (MMC) Interfaces
- SATA Interfaces
- SD Card Interfaces
- SIM Ports
- MDDI Ports
- MPPI Ports

Dimensions and Pin Configuration



Marking:3304P



Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	Ppk	80	W
Peak Pulse Current (8/20 μs)	I _{PP}	4	A
ESD per IEC 61000-4-2 (Air)	VESD	± 25	kV
ESD per IEC 61000-4-2 (Contact)		± 20	
Operating Temperature Range	T _J	-55 to +125	$^{\circ}\text{C}$
Storage Temperature Range	T _{stg}	-55 to +150	$^{\circ}\text{C}$

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V _{RWM}			3.3	V	Any I/O pin to ground
Breakdown Voltage	V _{BR}	3.5			V	I _T = 1mA, any I/O pin to ground
Reverse Leakage Current	I _R			0.5	μA	V _{RWM} = 3.3V, any I/O pin to ground
Clamping Voltage	V _C			8	V	I _{PP} = 1A (8 x 20 μs pulse), any I/O pin to ground
Clamping Voltage	V _C			16	V	I _{PP} = 4.0A (8 x 20 μs pulse), any I/O pin to ground
Junction Capacitance	C _J		0.4		pF	V _R = 0V, f = 1MHz, any I/O pin to ground
Junction Capacitance	C _J		0.25	0.35	pF	V _R = 0V, f = 1MHz, between I/O pins

Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise Specified)

Fig1. 8/20 μs Pulse Waveform

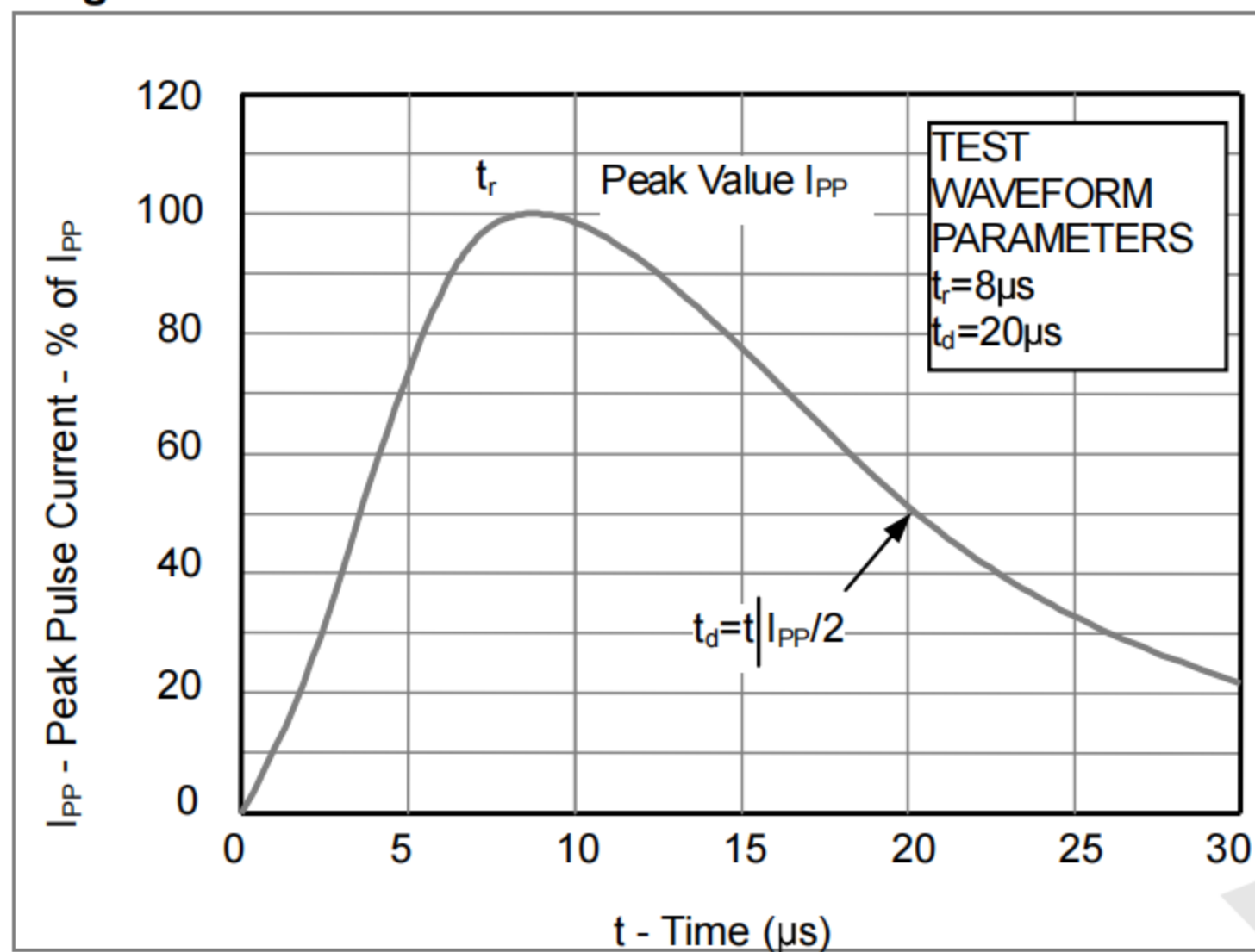


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

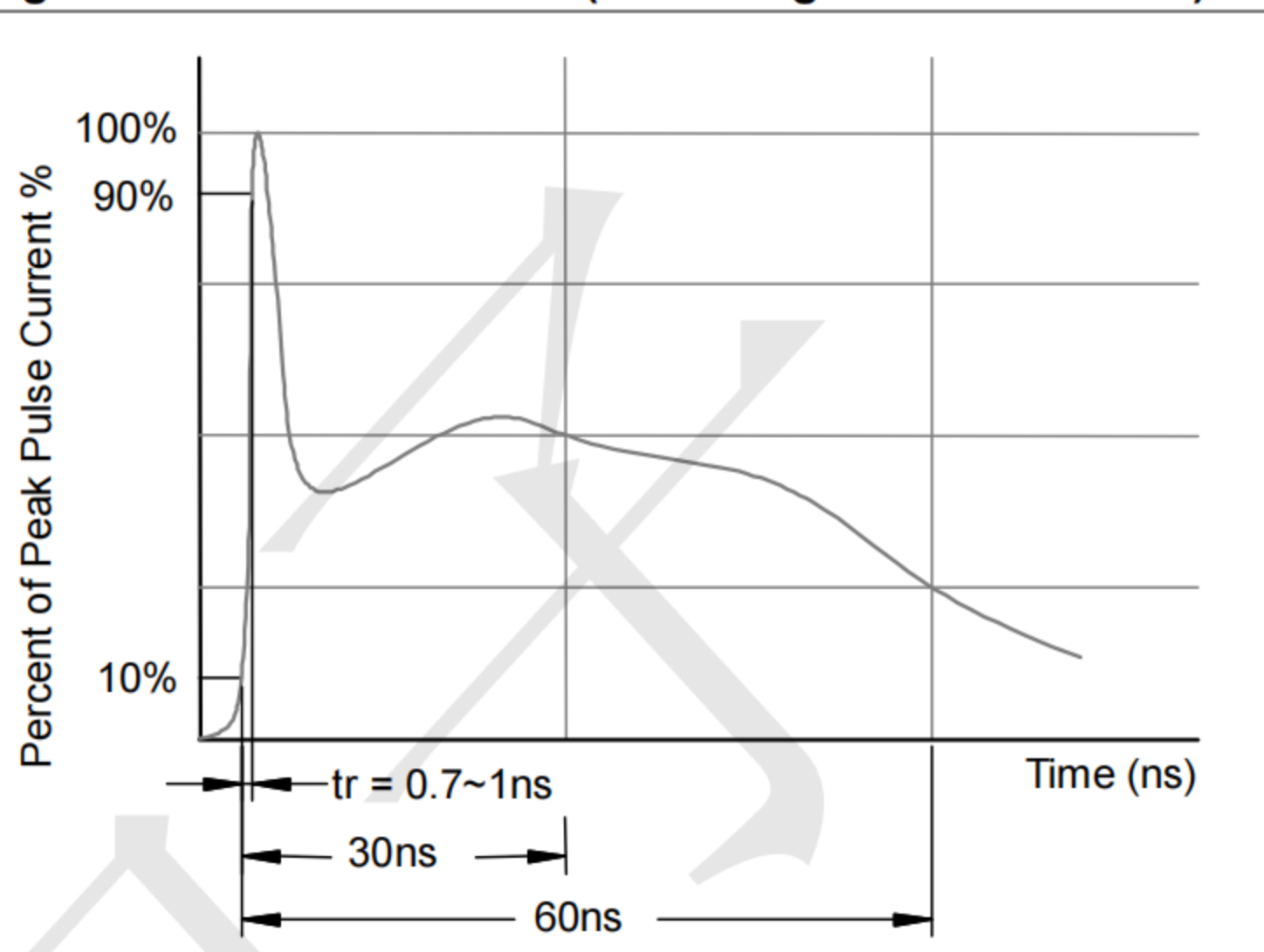
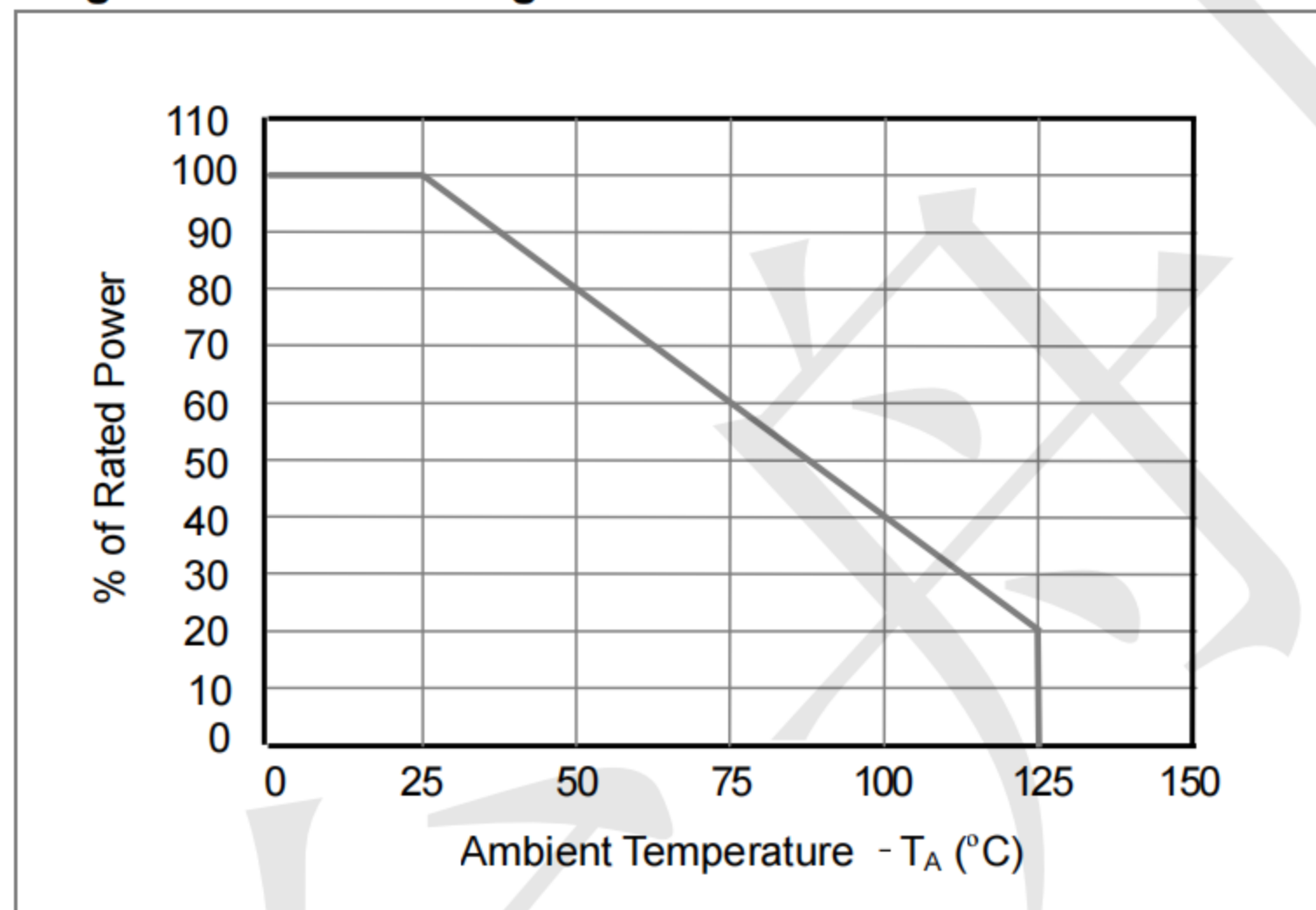
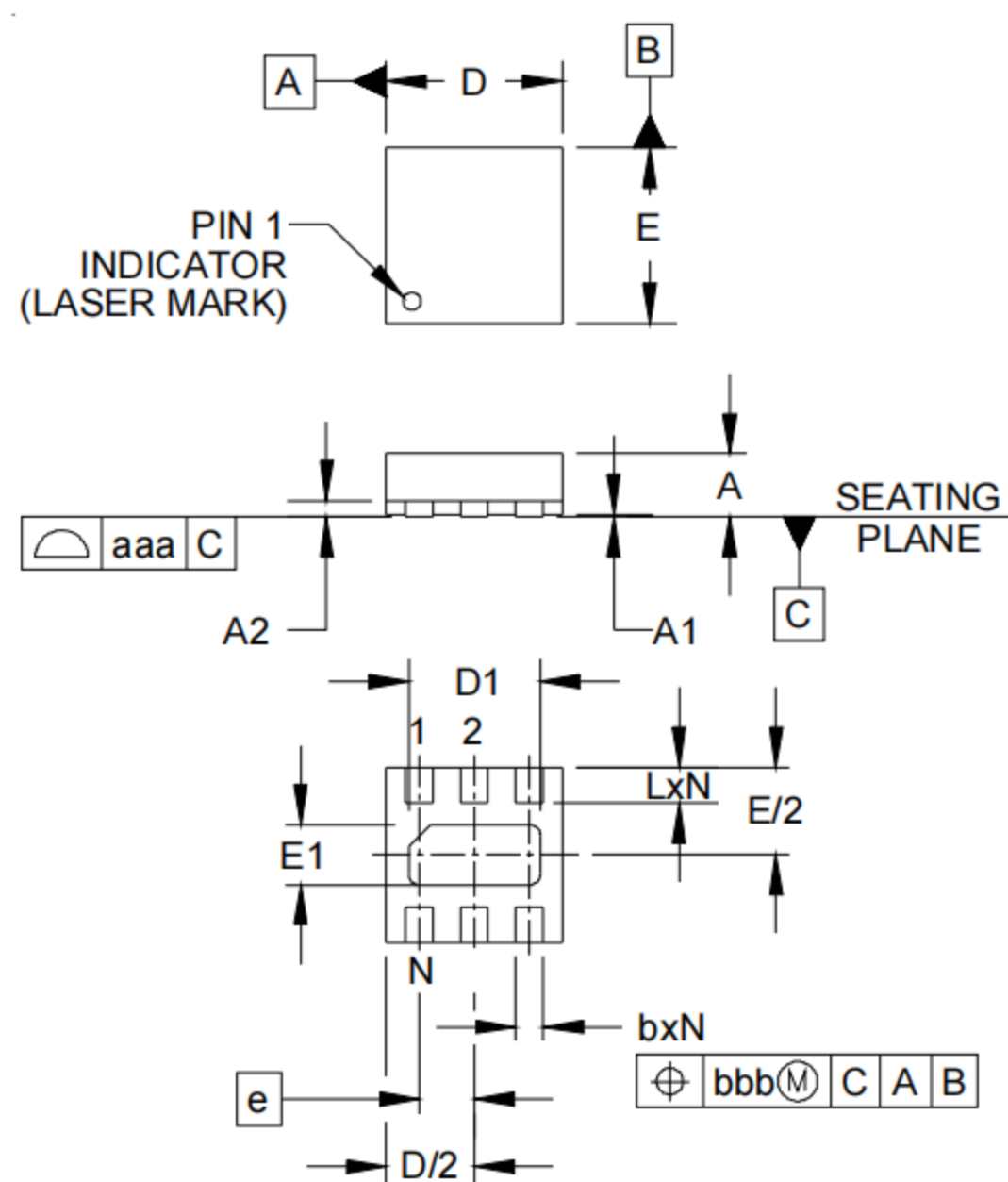


Fig3. Power Derating Curve

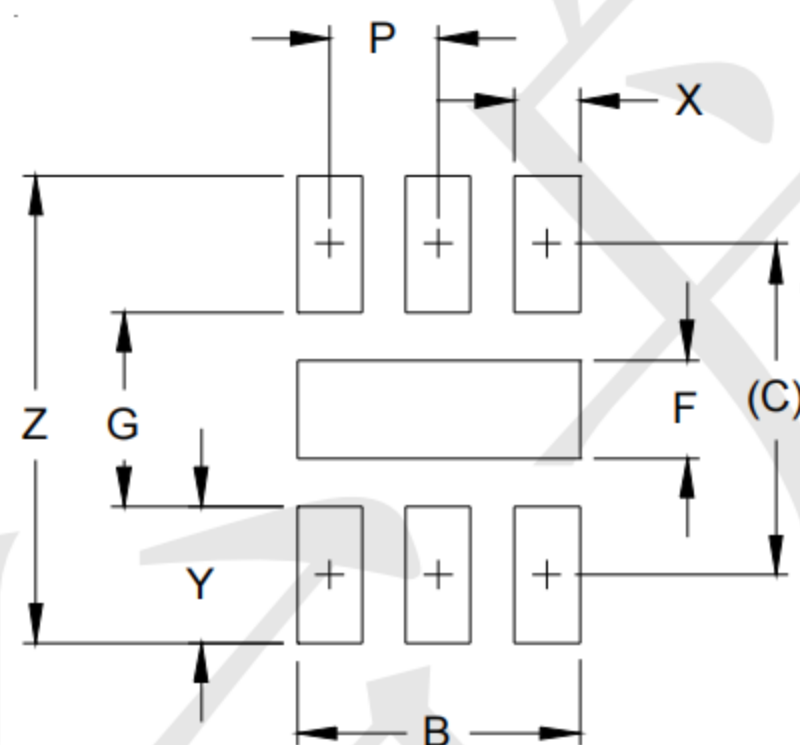


Outline Drawing -DFN1616-6



DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	.020	.023	.026	0.50	0.58	0.65
A1	0.00	.001	.002	0.00	0.03	0.05
A2		(.006)			(0.15)	
b	.007	.010	.012	0.20	0.25	0.30
D	.059	.063	.067	1.50	1.60	1.70
D1	.041	.047	.051	1.05	1.20	1.30
E	.059	.063	.067	1.50	1.60	1.70
E1	.016	.022	.026	0.40	0.55	0.65
e	.020 BSC			0.50 BSC		
L	.013	.013	.016	0.25	0.33	0.40
N	6			6		
aaa	.004			0.09		
bbb	.004			0.09		

Land Pattern -DFN1616-6



DIM	INCHES		MILLIMETERS	
B	.051		1.30	
C	.060		1.52	
P	.020		0.50	
F	.018		0.45	
G	.035		0.89	
X	.012		0.30	
Y	.025		0.63	
Z	.085		2.15	